Response to Advisory Action Mailed October 23, 2002

PATENT

Express Mail Number EV140162004US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

David W. Carlson

Appln. No.: 09/678,414

Filed: October 2, 2000

For: METHOD FOR PLANARIZING A THIN

FILM

Group Art Unit: 2823

Examiner: B. Kebede

RESPONSE TO ADVISORY ACTION
MAILED OCTOBER 23, 2002

Commissioner for Patents Washington, D.C. 20231

Dear Sir:

In response to the Advisory Action mailed October 23, 2002, please amend the aboveidentified application as follows:

In the Claims

Claim 18 has been cancelled.

The claims have been amended to read as follows:

- 16. (Amended) The method of claim 1 wherein the layer of first material makes an electrical contact with a device on the wafer.
 - The method of claim 22 wherein the first lower level lies above 19. (Amended) the wafer upper level.
 - 20. (Amended) The method of claim 19 wherein the planarized layer of first material has a thickness over the wafer upper layer, and

Atty. Docket No.: 100-13601

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